

Nine-Output 3.3 V Buffer

Features

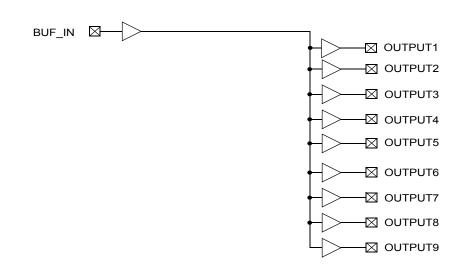
- One-input to nine-output buffer/driver
- Supports two DIMMs or four SO-DIMMs with one additional output for feedback to an external or chipset phase-locked loop (PLL)
- Low power consumption for mobile applications
 Less than 32 mA at 66.6 MHz with unloaded outputs
- 1-ns Input-output delay
- Buffers all frequencies from DC to 133.33 MHz
- Output-output skew less than 250 ps
- Multiple V_{DD} and V_{SS} pins for noise and electromagnetic interference (EMI) reduction
- Space-saving 16-pin 150-mil small-outline integrated circuit (SOIC) package
- 3.3 V operation
- Industrial temperature available

Logic Block Diagram

Functional Description

The CY2309NZ is a low-cost buffer designed to distribute high-speed clocks in mobile PC systems and desktop PC systems with SDRAM support. The part has nine outputs, eight of which can be used to drive two DIMMs or four SO-DIMMs, and the remaining can be used for external feedback to a PLL. The device operates at 3.3V and outputs can run up to 133.33 MHz.

The CY2309NZ is designed for low EMI and power optimization. It has multiple V_{SS} and V_{DD} pins for noise optimization and consumes less than 32 mA at 66.6 MHz, making it ideal for the low-power requirements of mobile systems. It is available in an ultra-compact 150-mil 16-pin SOIC package.





CY2309NZ

Contents

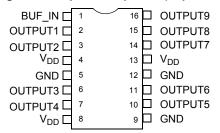
Pinouts	3
Pin Descriptions	3
Maximum Ratings	4
Operating Conditions	
Electrical Characteristics	
Switching Characteristics	5
Switching Waveforms	6
Test Circuits	
Ordering Information	
Ordering Code Definitions	
Package Diagram	

Acronyms	9
Document Conventions	
Units of Measure	9
Document History Page	10
Sales, Solutions, and Legal Information	11
Worldwide Sales and Design Support	
Products	11
PSoC® Solutions	11
Cypress Developer Community	11
Technical Support	



Pinouts

Figure 1. 16-pin SOIC pinout (Top View)



Pin Descriptions

Pin	Signal	Description	
4, 8, 13	V _{DD}	3.3 V Digital voltage supply	
5, 9, 12	GND	Ground	
1	BUF_IN	Input clock	
2, 3, 6, 7, 10, 11, 14, 15, 16	OUTPUT [1:9]	Outputs	



Maximum Ratings

Supply voltage to ground potential	–0.5 V to +7.0 V
DC input voltage	–0.5 V to 7.0 V

Storage temperature	–65 °C to +150 °C
Junction temperature	150 °C
Static discharge voltage	
(per MIL-STD-883, Method 3015)	>2,000 V

Operating Conditions

For Commercial and Industrial Temperature Devices

Parameter	Description	Min	Max	Unit
V _{DD}	Supply voltage	3.0	3.6	V
T _A	(Ambient operating temperature) commercial	0	70	°C
	(Ambient operating temperature) industrial	-40	85	°C
CL	Load capacitance, Fout < 100 MHz	-	30	pF
	Load capacitance,100 MHz < Fout < 133.33 MHz		15	pF
C _{IN}	Input capacitance	_	7	pF
BUF_IN, OUTPUT [1:9]	Operating frequency	DC	133.33	MHz
t _{PU}	Power-up time for all VDDs to reach minimum specified voltage (power ramps must be monotonic)		50	ms

Electrical Characteristics

For Commercial and Industrial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V _{IL}	Input LOW voltage [1]		-	0.8	V
V _{IH}	Input HIGH voltage [1]		2.0	_	V
IIL	Input LOW current	V _{IN} = 0 V	-	50.0	μA
I _{IH}	Input HIGH current	V _{IN} = V _{DD}	-	100.0	μΑ
V _{OL}	Output LOW voltage [2]	I _{OL} = 8 mA	_	0.4	V
V _{OH}	Output HIGH voltage [2]	I _{OH} = –8 mA	2.4	-	V
I _{DD}	Supply current	Unloaded outputs at 66.66 MHz	_	32	mA

Notes

BUF_IN input has a threshold voltage of V_{DD}/2.
 Parameter is guaranteed by design and characterization. It is not 100% tested in production.



Switching Characteristics

For Commercial and Industrial Temperature Devices ^[3]

Parameter	Description	Condition	Min	Тур	Max	Unit
	Duty cycle ^[4] = $t_2 \div t_1$	Measured at 1.4 V	40.0	50.0	60.0	%
t ₃	Rise time ^[4]	Measured between 0.8 V and 2.0 V	_	_	1.50	ns
t ₄	Fall time ^[4]	Measured between 0.8 V and 2.0 V	_	_	1.50	ns
t ₅	Output to output skew ^[4]	All outputs equally loaded	_	_	250	ps
t ₆	Propagation delay, BUF_IN Rising edge to Output Rising edge ^[4]	Measured at V _{DD} /2	1	5	9.2	ns

Notes
3. All parameters specified with loaded outputs.
4. Parameter is guaranteed by design and characterization. It is not 100% tested in production.



Switching Waveforms



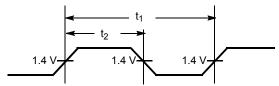


Figure 3. All Outputs Rise/Fall Time

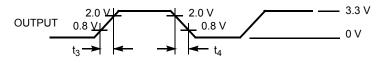


Figure 4. Output-Output Skew

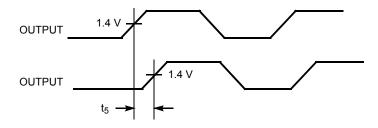
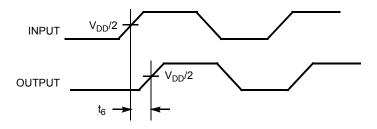
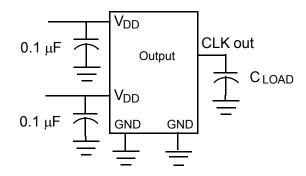


Figure 5. Input-Output Propagation Delay



Test Circuits

Figure 6. Test Circuits

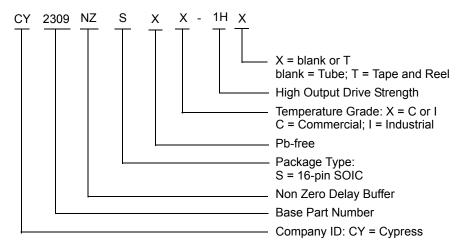




Ordering Information

Ordering Code	Package Type	Operating Range
Pb-free		
CY2309NZSXC-1H	16-pin SOIC (150 Mils)	Commercial
CY2309NZSXC-1HT	16-pin SOIC (150 Mils) – Tape and Reel	Commercial
CY2309NZSXI-1H	16-pin SOIC (150 Mils)	Industrial
CY2309NZSXI-1HT	16-pin SOIC (150 Mils) – Tape and Reel	Industrial

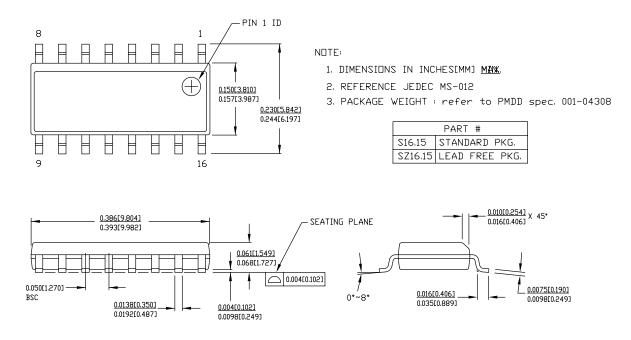
Ordering Code Definitions





Package Diagram

Figure 7. 16-pin SOIC (150 Mils) S16.15/SZ16.15 Package Outline, 51-85068



51-85068 *E



Acronyms

Acronym	Description	
EMI	Electromagnetic Interference	
PLL	Phase-Locked Loop	
SOIC	Small-Outline Integrated Circuit	

Document Conventions

Units of Measure

Symbol	Unit of Measure	
°C	degrees Celsius	
MHz	megahertz	
μA	microampere	
mA	milliampere	
ms	illisecond	
mV	nillivolt	
ns	nanosecond	
pF	picofarad	
V	volt	





Document History Page

Rev.	ECN	Orig. of	Submission	Description of Change
non	_0.1	Change	Date	
**	111858	DSG	12/09/01	Change from Spec number: 38-00709 to 38-07182
*A	121834	RBI	12/14/02	Power-up requirements added to Operating Conditions Information
*B	130563	SDR	10/23/03	Added industrial operating temperature to operating conditions
*C	212991	RGL / GGK	03/30/04	Updated the propagation delay T ₆ spec to 9.2 ns in the Switching Characteristics table
*D	270149	RGL	10/04/04	Added Lead-free devices Replaced 8.7 ns Input/Output Delay to 1 ns Input/Output Delaying the features section
*E	2568533	AESA	09/23/08	Changed "SDRAM [1:9]" to "OUTPUT [1:9]" in Operating Conditions table. Removed part number CY2309NZSI-1H and CY2309NZSI-1HT. Added Note "Not recommended for new designs." Updated template.
*F	2904715	CXQ	04/05/10	Removed parts CY2309NZSC-1H,CY2309NZSC-1HT from Ordering Information. Updated Package Diagram
*G	3082147	CXQ	11/10/2010	Maximum Rating section on page 2, change the following from: "DC Input Voltage (Except REF)0.5 V to VDD + 0.5 V" "DC Input Voltage REF0.5 V to 7.0 V" to: "DC Input Voltage0.5 V to 7.0 V" Updated footnotes Added Ordering Code Definitions. Added Acronyms and Units of Measure. Updated data sheet as per new template.
*H	4201460	CINM	11/25/2013	Updated Package Diagram: spec 51-85068 – Changed revision from *C to *E. Updated in new template. Completing Sunset Review.



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